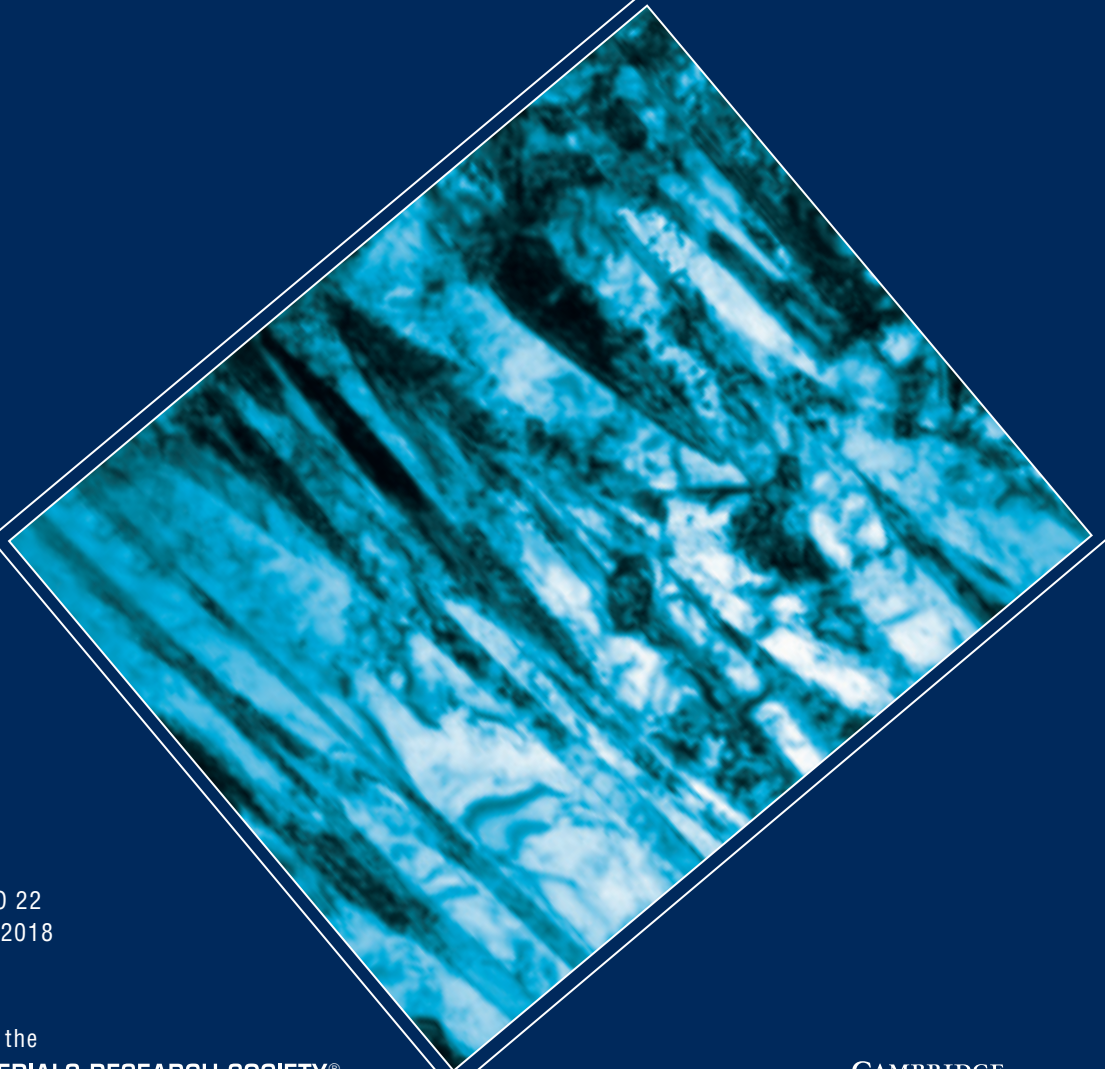




Journal of  
MATERIALS RESEARCH



VOLUME 33 • NO 22  
NOVEMBER 28, 2018

A publication of the

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# Journal of MATERIALS RESEARCH

Volume 33, Number 22, November 28, 2018

## INVITED PAPER

- 3657–3664 **Fused deposition modeling 3D printing of boron nitride composites for neutron radiation shielding**  
Smith Woosley,  
Nasim Abuali Galehdari,  
Ajit Kelkar, Shyam Aravamudhan

## ARTICLES

- 3665–3676 **Mechanical properties and chemical bonding of  $M_2B$  and  $M_2B_{0.75}C_{0.25}$  ( $M = Fe, Cr, W, Mo, Mn$ ) compounds**  
Yangzhen Liu, Hanguang Fu,  
Wei Li, Jiandong Xing, Yefei Li,  
Baochao Zheng
- 3677–3688 **Hot deformation behavior and processing maps of Ti–6Al–4V alloy with starting fully lamellar structure**  
Wenjing Zhang, Hua Ding,  
Jingwei Zhao, Bo Yang,  
Wenjing Yang
- 3689–3699 **Microstructure evolution of NiAl–Cr(Mo) planar eutectic lamellar structure during high temperature treatment**  
Lei Wang, Luhan Gao, Jun Shen,  
Yunpeng Zhang, Tao Wang,  
Zewei Wang, Pengfei Qu,  
Jianying Zhang, Guojun Zhang
- 3700–3710 **Investigation of microstructure and mechanical properties of the Cu–3% Ti alloy processed by multiaxial cryo-forging**  
Ramesh Sampath,  
Hanumanthappa Shivananda  
Nayaka, Karekere Rangaraju Gopi,  
Sandeep Sahu,  
Udaya Bhat Kuruveri

## INVITED FEATURE PAPER - REVIEW

- 3711–3738 **Review of microstructure and micromechanism-based constitutive modeling of polycrystals with a low-symmetry crystal structure**  
Irene J. Beyerlein, Marko Knezevic

## INVITED PAPER

- 3739–3749 **Strengthening mechanisms and deformability of nanotwinned AlMg alloys**  
Sichuang Xue, Qiang Li, Zhe Fan,  
Han Wang, Yifan Zhang, Jie Ding,  
Haiyan Wang, Xinghang Zhang

## INVITED FEATURE PAPER

- 3750–3761 **Fracture ab initio: A force-based scaling law for atomistically informed continuum models**  
Johannes J. Möller, Erik Bitzek,  
Rebecca Janisch,  
Hamad ul Hassan,  
Alexander Hartmaier

## ARTICLES

- 3762–3773 **Mapping dislocation densities resulting from severe plastic deformation using large strain machining**  
Sepideh Abolghasem,  
Saurabh Basu, Shashank Shekhar,  
M. Ravi Shankar
- 3774–3784 **Electrochemical and kinetic performance of amorphous/nanostructured TiNi-based intermetallic compound with Nb substitution synthesized by mechanical alloying**  
Roozbeh Abbasi,  
Seyed Farshid Kashani-Bozorg
- 3785–3792 **Influence of pulse repetition rate on the growth of cobalt-doped ZnO thin films by pulsed electron beam ablation**  
Asghar Ali, Redhouane Henda

(Continued)

- 3793–3800 **Corrosion-resistant fluoridated Ca–Mg–P composite coating on magnesium alloys prepared via hydrothermal assisted sol–gel process**  
Yangyang Jiang, Lingjun Zhu, Shu Cai, Sibao Shen, Yue Li, Song Jiang, Yishu Lin, Shaoshuai Hua, Rui Ling, Guohua Xu
- 3801–3808 **Effect of Cu on the corrosion resistance and electrochemical response of a Ni–Co–Cr–Mo alloy in acidic chloride solution**  
Biaobiao Yang, Chenying Shi, Yunping Li, Qian Lei, Yan Nie
- 3809–3817 **Microstructure and mechanical properties of ultrafine-grained titanium processed by multi-pass ECAP at room temperature using core–sheath method**  
Alireza Derakhshandeh, Hamed Shahmir, Mahmoud Nili-Ahmadabadi
- 3818–3826 **Preparation of superhydrophobic and superoleophobic Al–Mg alloy surface via simple, environmentally friendly method**  
Ning Ma, Yang Chen, Shuguo Zhao, Jingchun Li, Baofeng Shan, Juhe Sun
- 3827–3840 **Enhanced fatigue performance and surface mechanical properties of AISI 304 stainless steel induced by electropulsing-assisted ultrasonic surface rolling process**  
Hai-bo Wang, Xin-hua Yang, He Li, Guo-lin Song, Guo-yi Tang
- 3841–3848 **Unusual irradiation-induced disordering in Cu<sub>3</sub>Au near the critical temperature: An in situ study using electron diffraction**  
Calvin Robert Lear, Robert S. Averback, Pascal Bellon, Andrea E. Sand, Marquis A. Kirk
- 3849–3856 **Determination of directionality of nonequibiaxial residual stress by nanoindentation testing using a modified Berkovich indenter**  
Jong-hyoung Kim, Huiwen Xu, Min-Jae Choi, Eunju Heo, Young-Cheon Kim, Dongil Kwon
- 3857–3869 **Highly efficient solar steam generation by hybrid plasmonic structured TiN/mesoporous anodized alumina membrane**  
Yue Bian, Kun Tang, Zhonghua Xu, Jingrui Ma, Yang Shen, Licai Hao, Xuanhu Chen, Kuiying Nie, Jing Li, Tongchuan Ma, Shunming Zhu, Jiandong Ye, Xiang Xiong, Yi Yang, Rong Zhang, Youdou Zheng, Shulin Gu
- 3870–3879 **Ultrafine bamboo-char as a new reinforcement in poly(lactic acid)/bamboo particle biocomposites: The effects on mechanical, thermal, and morphological properties**  
Shaoping Qian, Yingying Tao, Yiping Ruan, Cesar A. Fontanillo Lopez, Linqiong Xu
- 3880–3889 **Linear, third order nonlinear and optical limiting studies on MZO/FTO thin film system fabricated by spin coating technique for electro-optic applications**  
Mohd. Shkir, Mohd. Arif, Vanga Ganesh, Mohamed A. Manthrammel, Arun Singh, Shivaraj R. Maidur, Parutagouda Shankaragouda Patil, Ibrahim S. Yahia, Hamed Algarni, Salem AlFaify